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(12) **United States Design Patent**
Faith et al.

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(54) **ELECTRICAL CONNECTOR**

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(73) Assignee: **SAMTEC, INC.**, New Albany, IN (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/611,521**

(22) Filed: **Jul. 21, 2017**

(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/147**

(58) **Field of Classification Search**
USPC D13/123, 133, 146, 147, 154, 184, 199
CPC H01R 12/51; H01R 12/52; H01R 12/57; H01R 12/592; H01R 12/61; H01R 12/63; H01R 12/7005; H01R 12/716; H01R 12/72; H01R 12/732; H01R 12/777; H01R 12/79; H01R 12/87; H01R 12/89; H01R 13/213; H01R 13/2464; H01R 13/2492; H01R 13/26; H01R 13/28; H01R 13/428; H01R 13/434; H01R 13/4362; H01R 13/4534; H01R 13/506; H01R 13/508; H01R 13/5804; H01R 13/5816; H01R 13/585; H01R 13/6271; H01R 13/635
See application file for complete search history.

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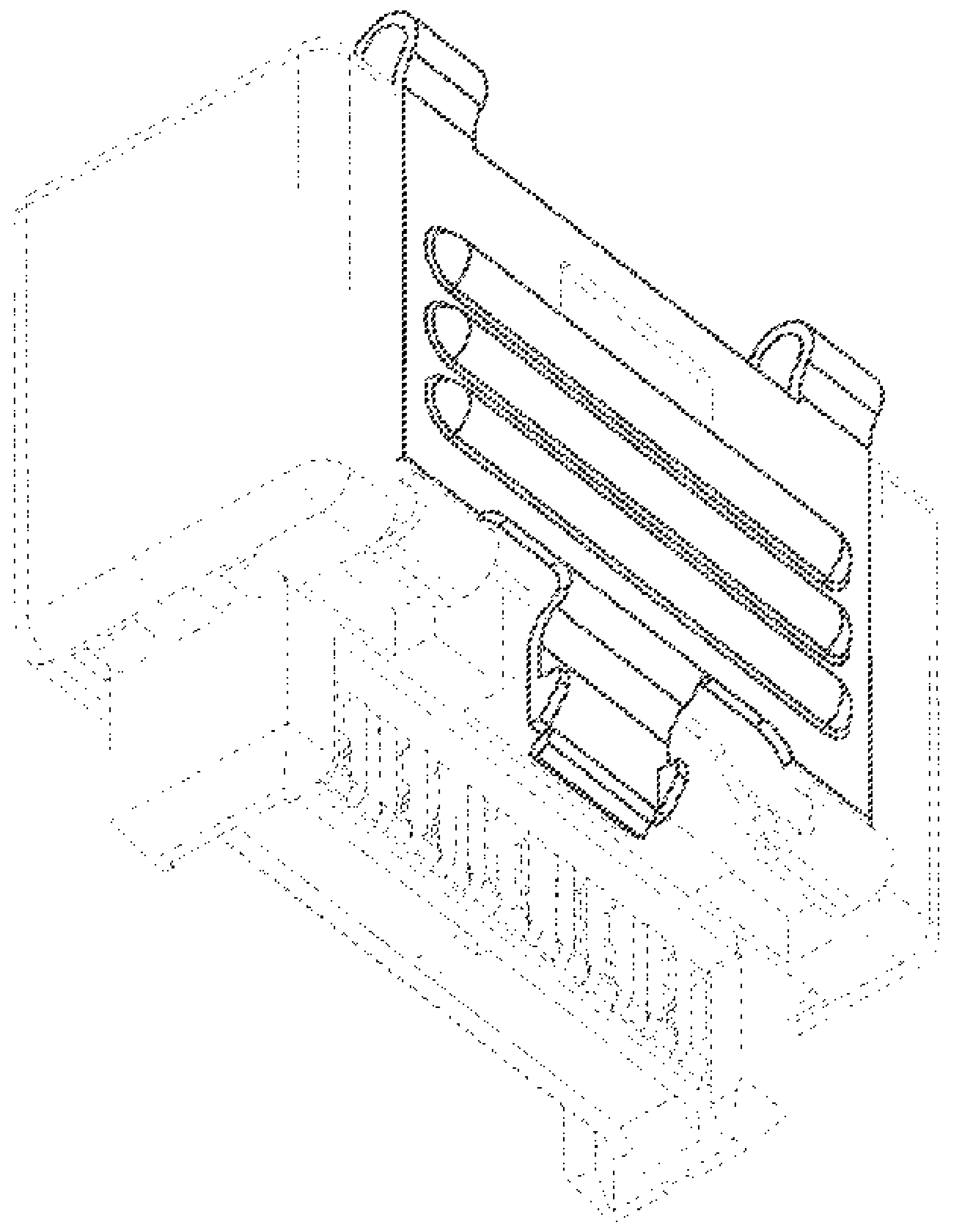
(57) **CLAIM**

The ornamental design for an electrical connector, as shown and described.

DESCRIPTION

FIG. **1** is a top, right, front perspective view of an electrical connector showing the new design;
FIG. **2** is a top, front and right side perspective view thereof;
FIG. **3** is a top, rear and left side perspective view thereof;
FIG. **4** is a bottom, front and right side perspective view thereof;
FIG. **5** is a bottom plan view thereof;
FIG. **6** is a top plan view thereof,
FIG. **7** is a left side elevation view thereof;
FIG. **8** is a right side elevation view thereof;
FIG. **9** is a rear elevation view thereof; and,
FIG. **10** is a front elevation view thereof.
The broken lines shown represent the portions of the electric connector that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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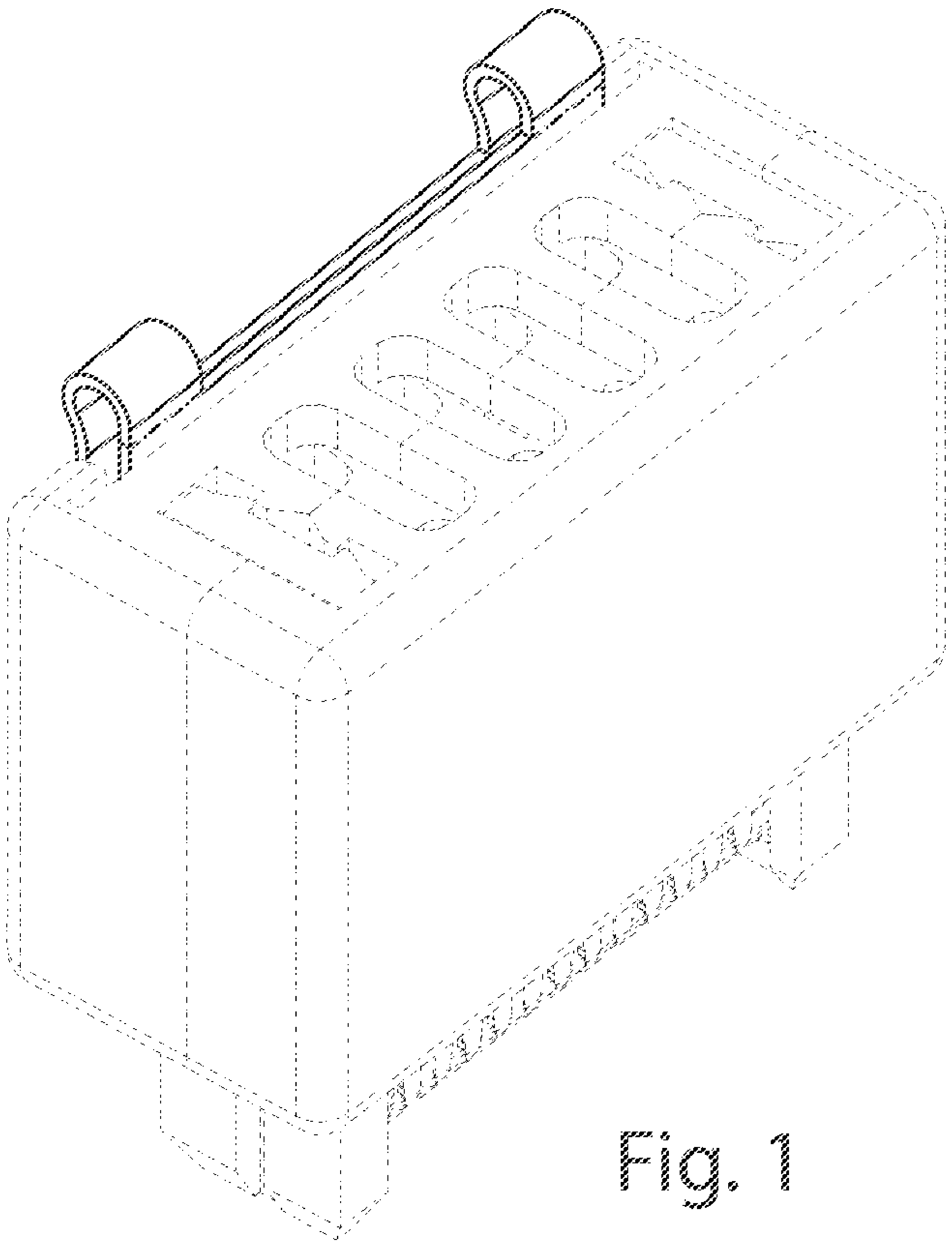


Fig. 1

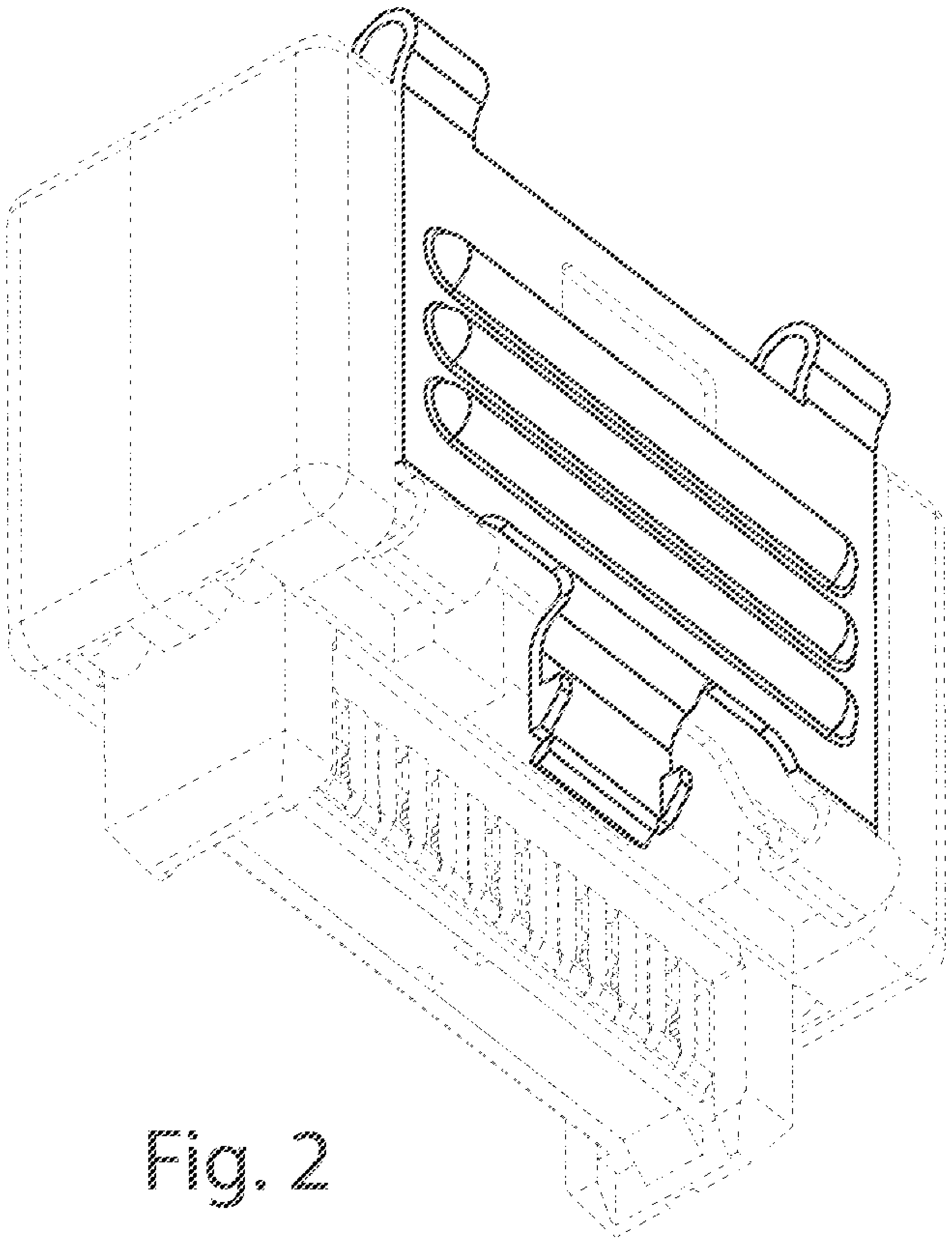
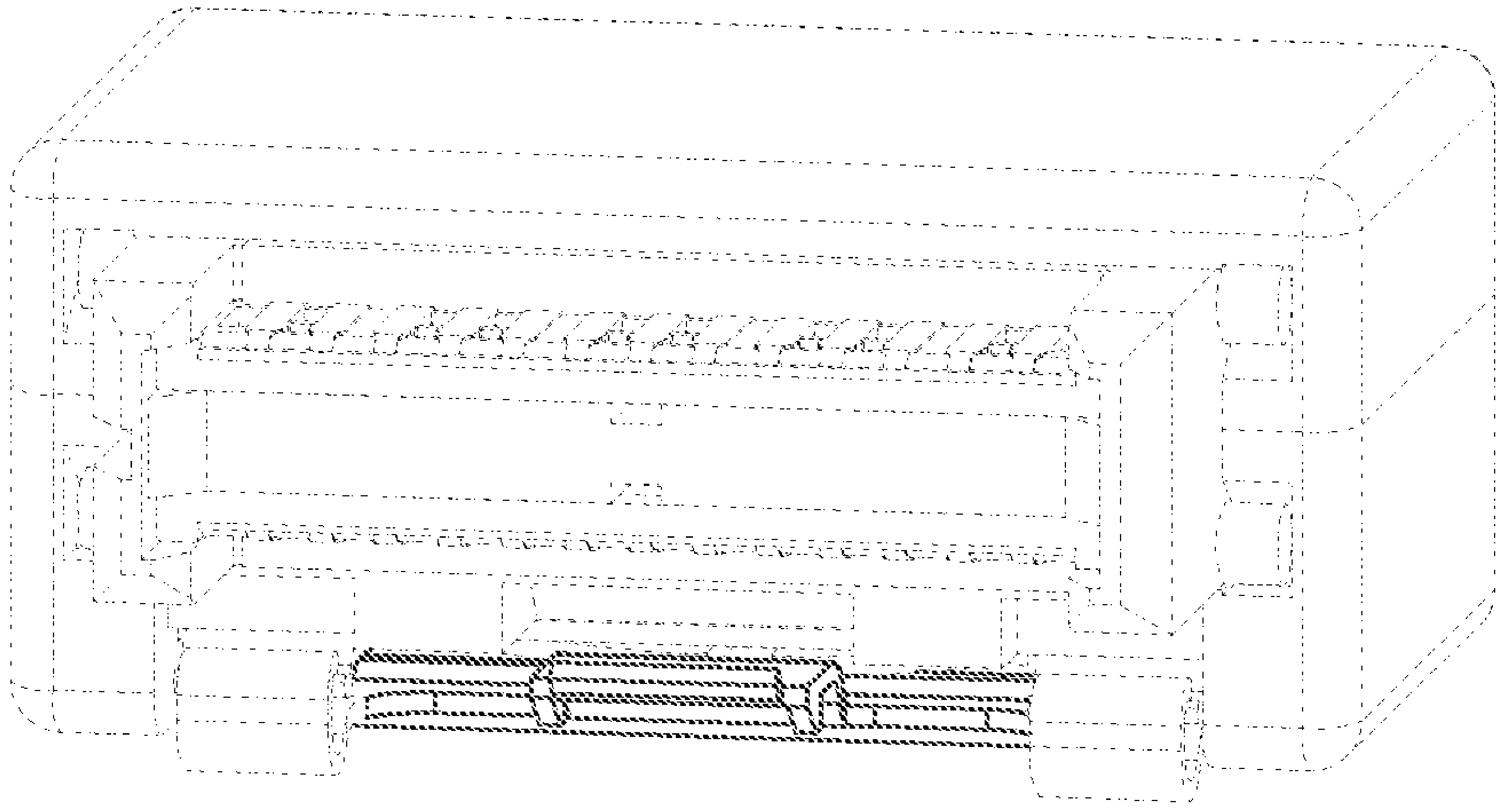


Fig. 2



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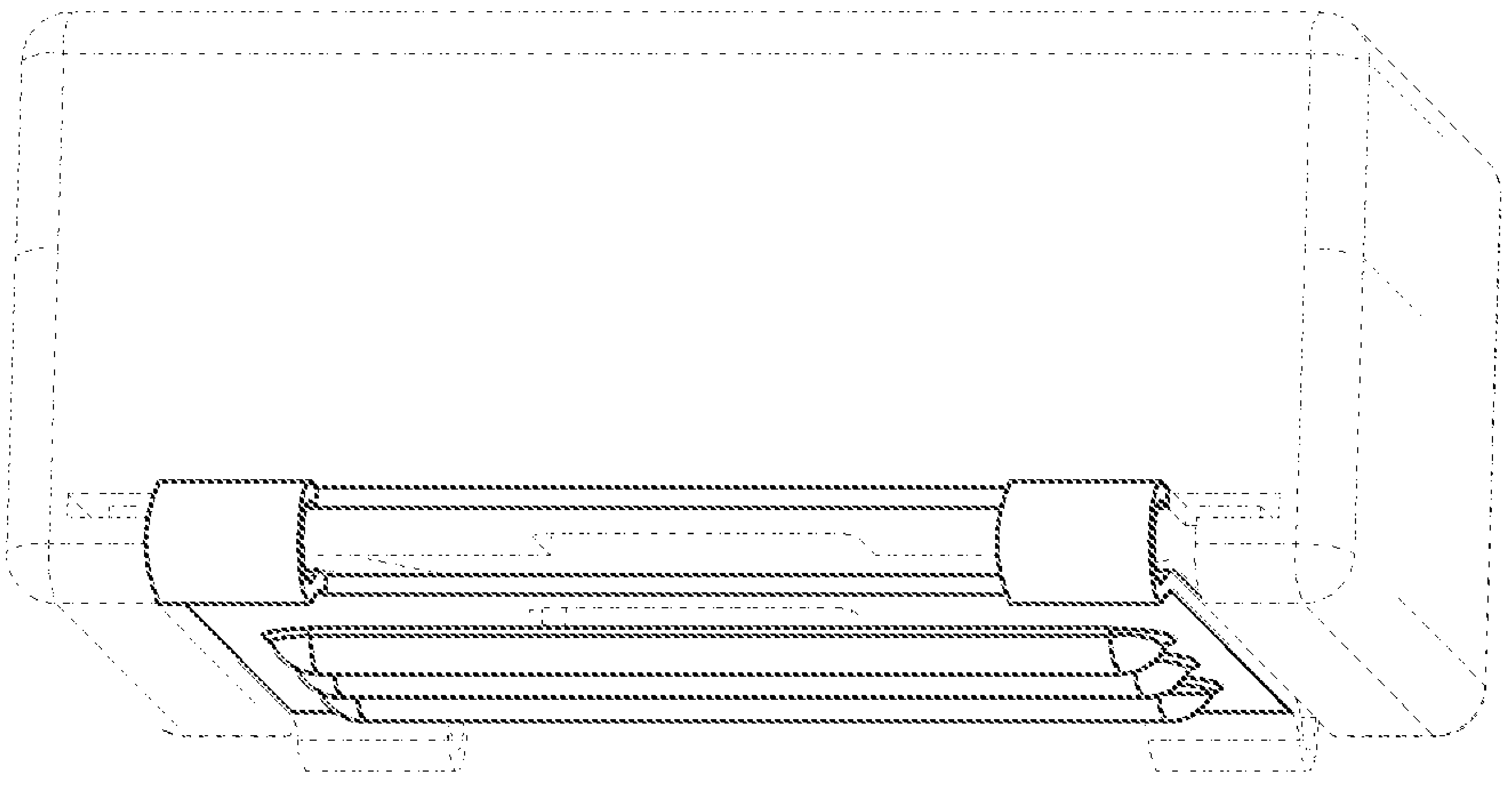

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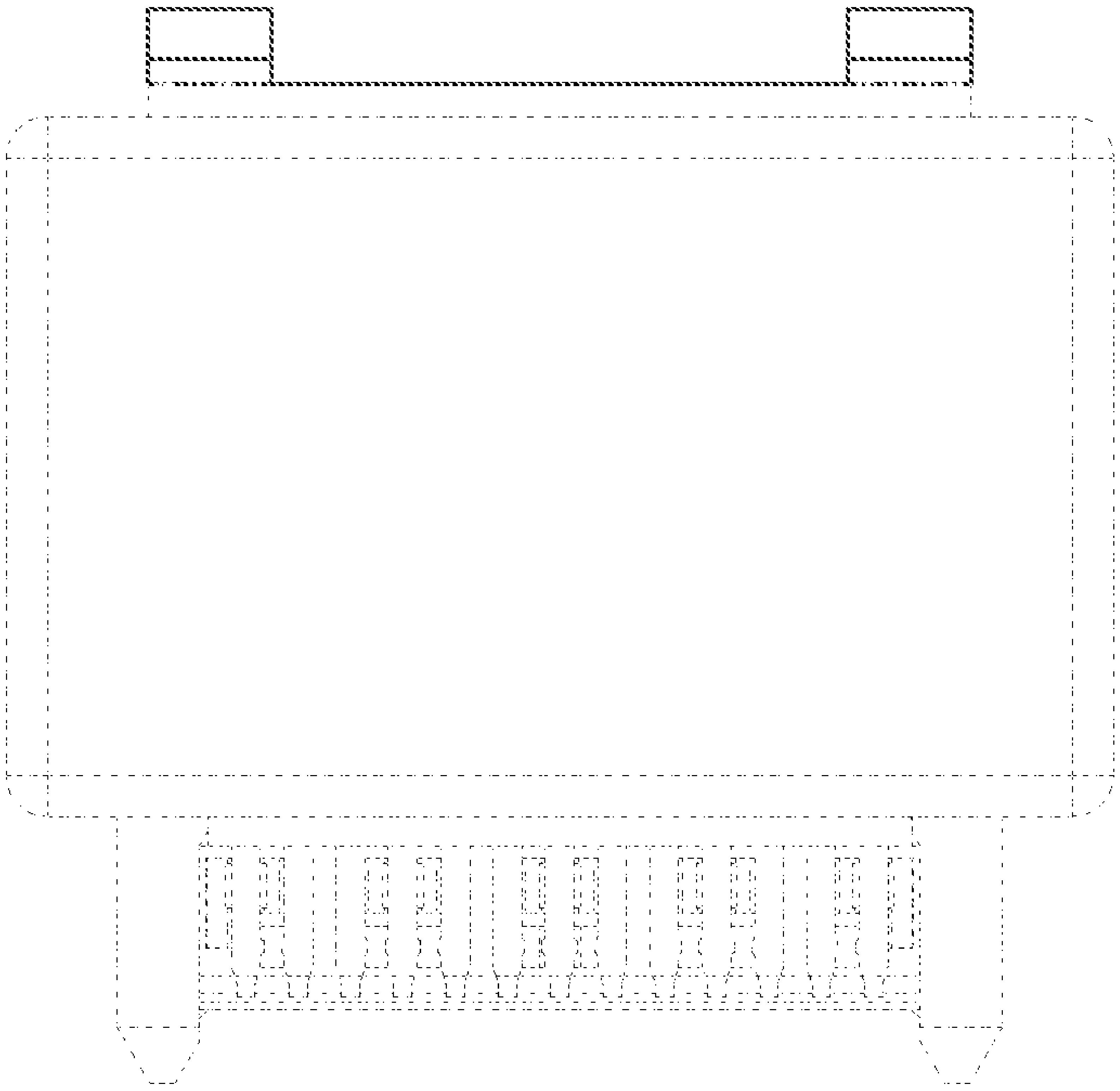

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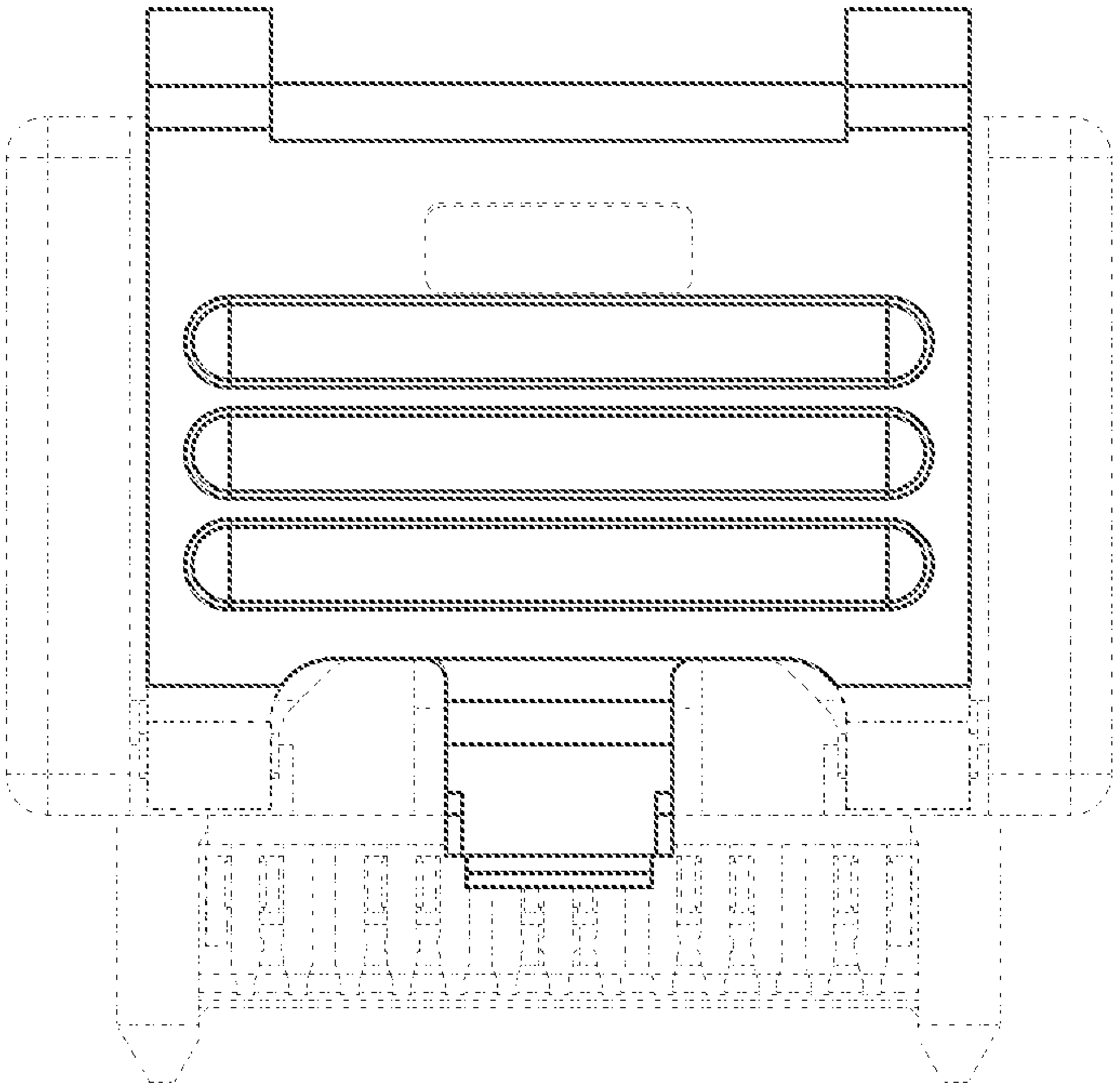

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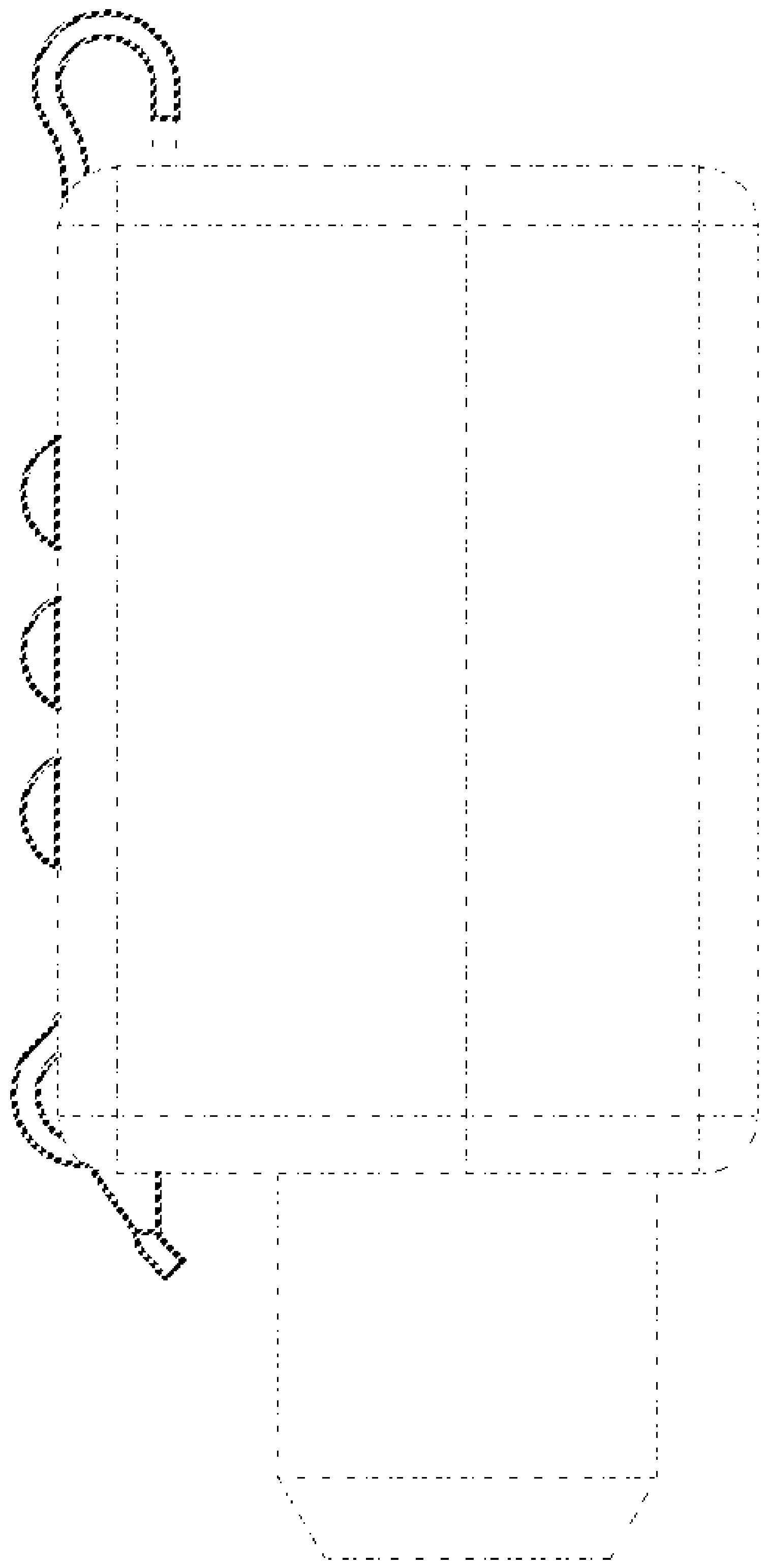

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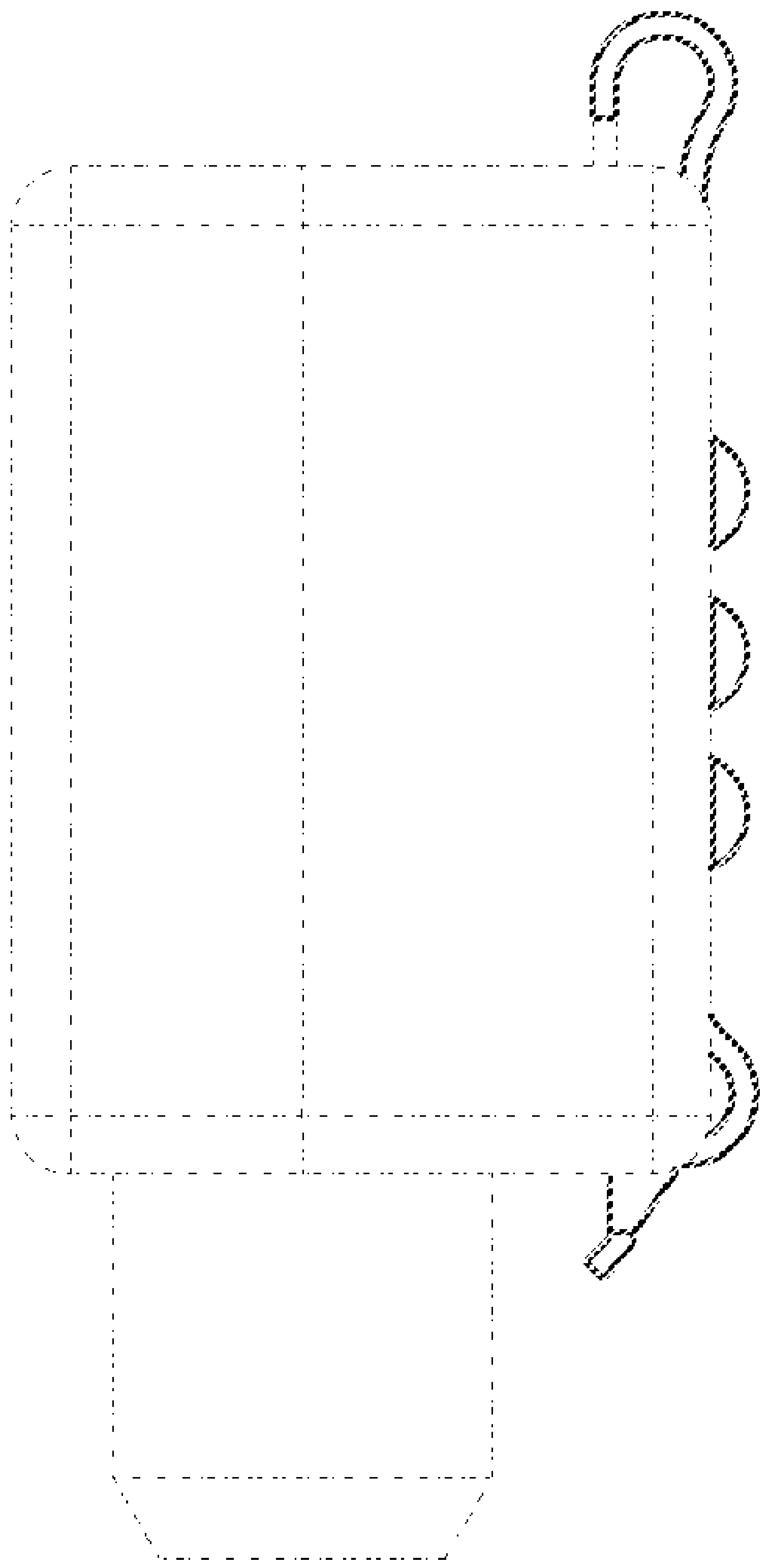

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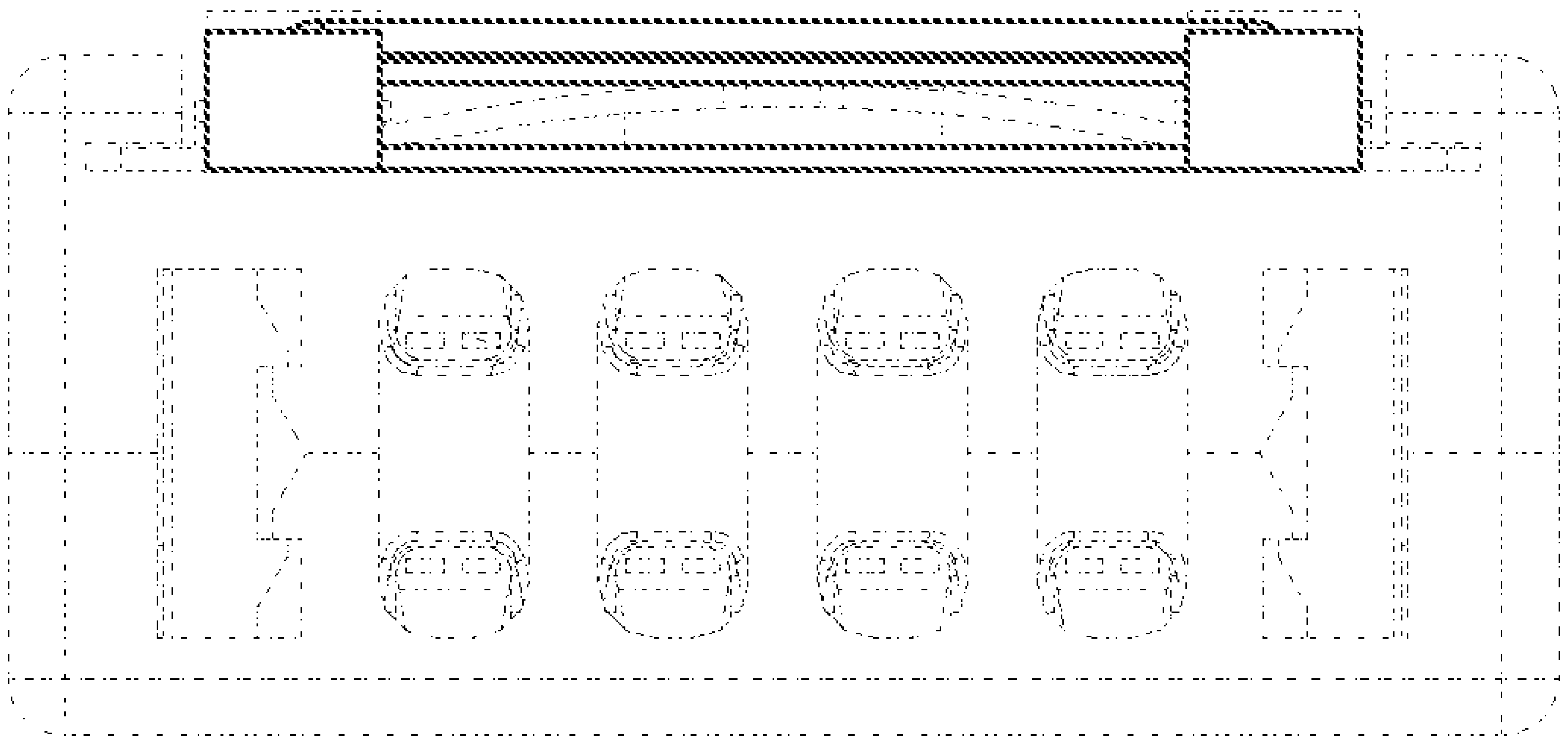

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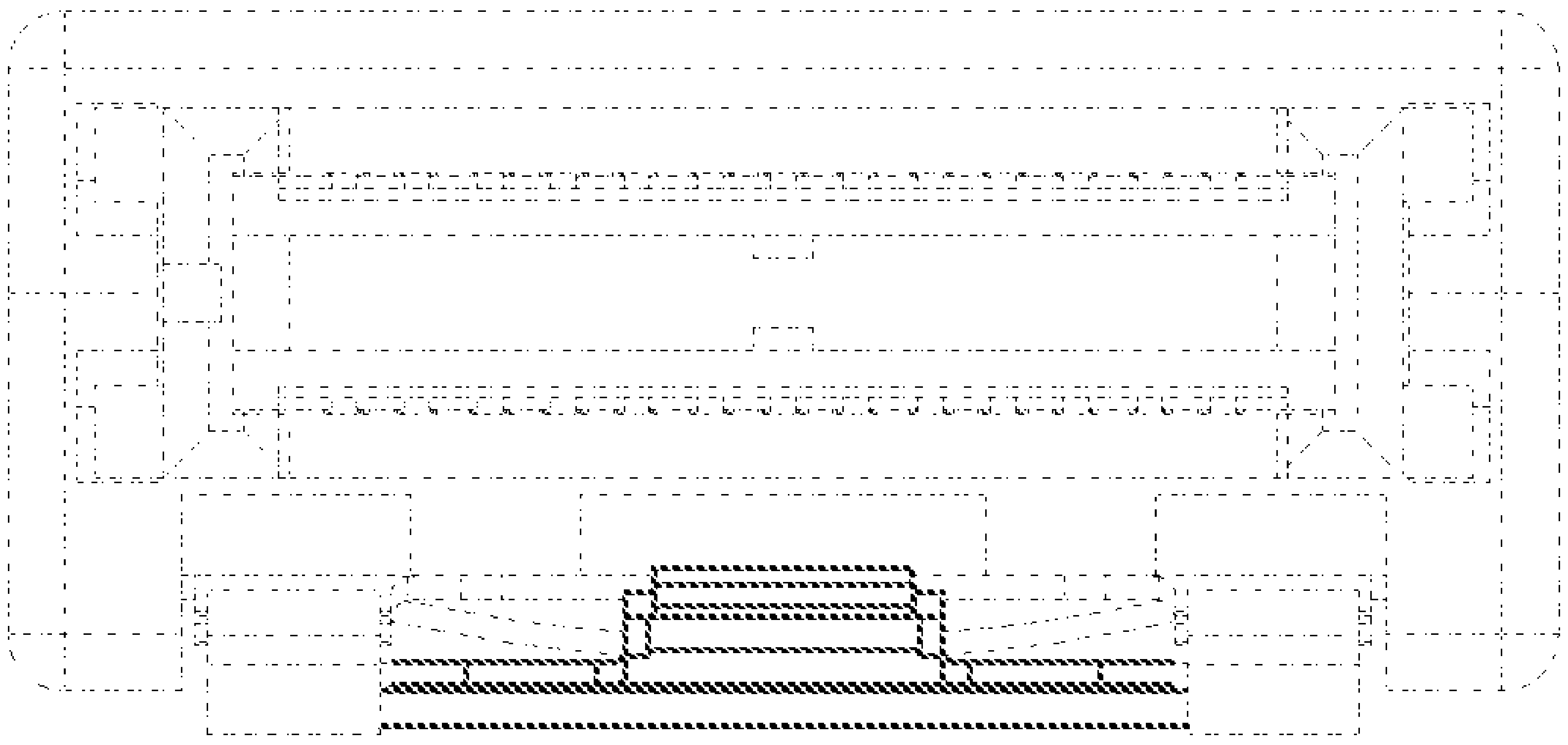

Fig. 10